

IN THE CLAIMS:

Please cancel claims 1 - 7 of the International Application and replace them with new claims 8 - 12. The status of the claims after amendment will be as follows:

Claims 1 - 7 (cancelled)

8. (new) A method of interconnecting terminals comprising: placing terminals so as to oppose each other with an anisotropic electrically conductive resin composition including at least electrically conductive particles and a resin component which is not completely cured at the melting point of the electrically conductive particles disposed between the opposing terminals;

heating the resin composition to a temperature which is higher than the melting point of the electrically conductive particles and at which the resin component is not completely cured, wherein in the heating, the electrically conductive particles collect between the opposing terminals by melting and agglomeration of the electrically conductive particles, and the opposing terminals are electrically interconnected; and curing the resin component.

9. (new) A method of interconnecting terminals as claimed in claim 8 wherein the resin component comprises a resin having reducing properties which can reduce at least one of the surface

of the terminals and the surface of the electrically conductive particles.

10. (new) A method of interconnecting terminals as claimed in claim 8 including completely filling the space between members on which the terminals are provided with the resin composition.

11. (new) A method of mounting a semiconductor device comprising:

placing electrode pads of a semiconductor chip opposite circuit electrodes provided on a circuit substrate so as to correspond to the electrode pads with an anisotropic electrically conductive resin composition including at least electrically conductive particles and a resin component which is not completely cured at the melting point of the electrically conductive particles disposed between the opposing electrode pads and circuit electrodes;

heating the resin composition to a temperature which is higher than the melting point of the electrically conductive particles and at which the resin component is not completely cured, wherein in the heating, the electrically conductive particles collect between the opposing electrode pads and circuit electrodes by melting and agglomeration of the electrically conductive particles, and the opposing electrode pads and circuit electrodes are electrically interconnected; and curing the resin component.

12. (new) A mounting method as claimed in claim 11 including completely filling the space between the semiconductor chip and the circuit substrate with the resin composition.